EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	0	(method and fabricating and chip\$1scale and package and comprising and positioning and preformed and polymeric and film and including and least and one and aperture and extends and substantially and longitudinally and therethrough and over and semiconductor and device and substantial and alignment and corresponding and bond and pad and selectively and introducing and conductive and material and partially and liquid and state).clm.	US-PGPUB	OR .	ON	2007/02/28 19:52
S1	1	."09832160".rlan. or ("09".src. and "832160".ap.)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2007/02/28 19:50
S2	154	("20010006759" "20030038378" "4341594" "4618878" "4803147" "4948754" "5049980" "5111279" "516 8346" "5207887" "5275973" "5299730" "5323060" "5347162" "5366996" "5384488" "5410805" "546868 1" "5489804" "55504035" "5506756" "5527741" "55554887" "55659033" "5559963" "5658827" "5672912" " 5677576" "5579977" "5583942" "5770889" "5814894" "5821624" "5834799" "5834884" "5834798" "1584 4304" "5851911" "5886415" "5907787" "5925931" "5946555" "5971253" "5977641" "6030889" "604310 9" "6054761" "6069071" "6071810" "6072236" "6117539" "6132587" "6165885" "6172559" "6172569" "6179200" "6181569" "6181569" "6172572" "6212767" "6233184" "6255737" "6284563" "6294407" "6306680" "631 9810" "6334249" "6343171" "6348731" "6376904" "6392306" "6458231" "6475896" "6475896" "6592200" "651537	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:16
S3	. 28	kapton with temperature with solder\$	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR'	ON	2007/02/20 13:19
59	4	"420" adj "degree.c"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:21
S10	18	"450" adj "degree.c"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:21
S11	1462	*450.degree.c*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	ON	2007/02/20 13:21
S12	279	"420.degree.c"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:21
S13	o	"420.degree.c" with (polyimide kapton)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/02/20 13:22
S14		(*450.degree.c" *450" adj "degree.c") with (polyimide kapton)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:24
S15	1721	(polyimide kapton) with (stabl\$ stabil\$) with temperature	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:24
S16	· 1089	(polyimide kapton) with (stabl\$ stabil\$) with high with temperature .	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:30
S18	66	(aluminum adj tin alsn al\$1sn) with (polyimide kapton)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:26
S19	10257385	@ad>"19990627" @rlad>"19990627" @pt1d>"19990627"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:30
S21	735	S16 not S19	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:39

EAST Search History

S22	62	melting adj point with (alsn al\$1sn al adj sn)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 13:55
S23	3374	melting adj point with sn	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 16:53
S24	189544	light adj emitting adj diode	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 16:54
S25	2	(light adj emitting adj diode led) with bond\$ adj pad with volume	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 17:23
S26	517	(light adj emitting adj diode led) with submount	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 17:23
S27	4807	(bond\$ adj pad solder) with volume	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 17:23
S28	19	S26 and S27	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 17:24